

新品承认书

NEW PRODUCT APPROVED

客户名称 (CUSTOMERS) _____

客户 P/N (CUSTOMER P/N) _____

升谱 P/N (SUNPU P/N) _____ NEPS-3022AG-G _____

产品说明 (DESCRIPTION) 0.3 英寸双八 共阳 黄绿色显示

送样日期 (SAMPLE DATE) _____

产品说明书 Specification	<input checked="" type="checkbox"/>	检验报告 INSPECTION	<input type="checkbox"/>	样品 SAMPLE	<input type="checkbox"/>	其它 OTHERS	<input type="checkbox"/>
核准 (APPROVED BY)	审核 (CHECKED BY)	校对 (PROOFREAD BY)	制作 (PREPARED BY)				

更改履历表

版本 Version	日期 date	描述	编制 Maker

客户判定结果 (CUSTOMER VERDICT)

承认(OK)

不承认(NG)

承认签名(APPROVED BY):

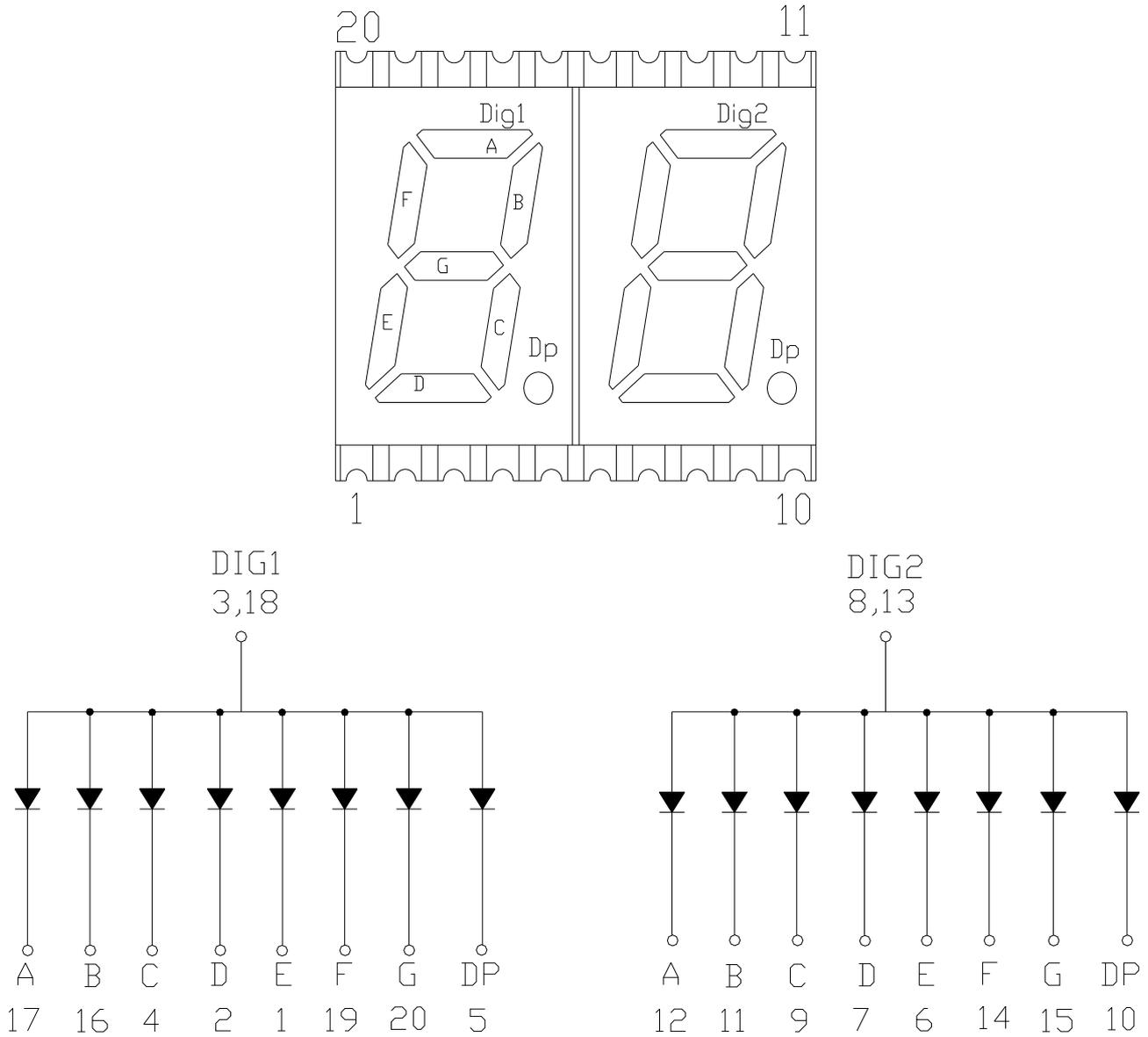
承认时间(APPROVED DATE):

改善意见(IMPROVED ADVICE):

说明: 为了能更好的服务客户, 请及时回传以上信息

REMARK: FOR OFFERING THE BEST SERVICE TO CUSTOMER, PLEASE FAX THE DATA TO FACTORY

4. 产品线路图 INTERNAL CIRCUIT DIAGRAM

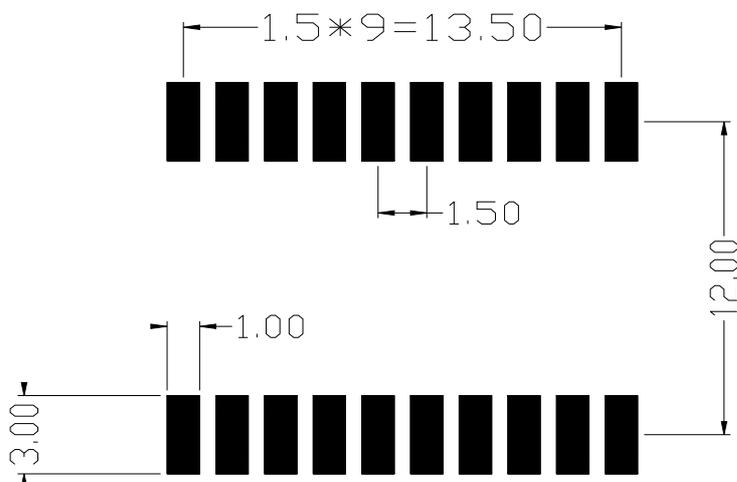


5、产品最大绝对参数值 (Ta: 25°C) ABSOLUTE MAXIMUM RATINGS AT Ta=25°C:

参数 (PARAMETER)	最大值 Max.	单位 UNIT
每段功耗 Power Dissipation Per Segment	52	mW
每段峰值电流 Peak Forward Current Per Segment (1/10duty cycle 0.1ms pulse width)	100	mA
每段平均正向电流 Average Forward Current Per Segment	20	mA
从室温线性减少 Derating Linear From 25°C Per Segment	0.33	mA/°C
每段反向电压 Reverse Voltage Per Segment	5	V
工作条件温度 Operating Temperature Range	-40°C to + 105°C	
储存温度 Storage Temperature Range	-40°C to + 105°C	
距离胶体 1.6mm 焊接, 温度 260°C , 焊接时间最多 3 秒 Lead Soldering Temperature 260°C at 1.6mm From Body for 3 seconds		

6、产品光电参数值 (Ta: 25°C) ELECTRICAL/OPTICAL CHARACTERISTICS AT Ta=25°C:

参数 PARAMETER	符号 SYMBOL	MIN.	TYP.	MAX.	UNIT	测试条件 Test condition
每段亮度 Luminous Intensity Per Segment	I_v	—	15	—	mcd	$I_F=10mA$
主波长 Dominant Wavelength	λ_d	—	570	—	nm	$I_F=20mA$
光谱半宽度 Spectral Line Half-Width	$\Delta\lambda$	—	30	—	nm	$I_F=20mA$
每颗正向电压 Forward Voltage Per Dice	V_F	—	2.0	2.6	V	$I_F=20mA$
每颗反向电流 Reverse Current Per Dice	I_R	—	—	50	μA	$V_R=5V$

7、推荐使用的焊盘尺寸 Recommended Soldering Pattern:


8、电气/光学特性曲线 Electrical / Optical Characteristics Curves:

(Ta = 25°C Unless Otherwise Noted)

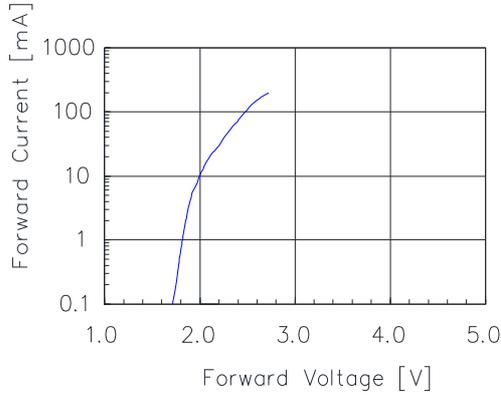


Fig 1. Forward Current vs. Forward Voltage

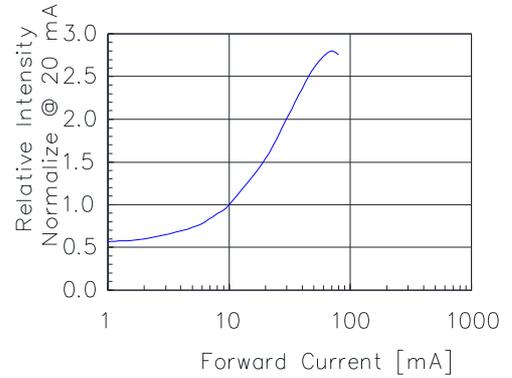


Fig 2. Relative Intensity vs. Forward Current

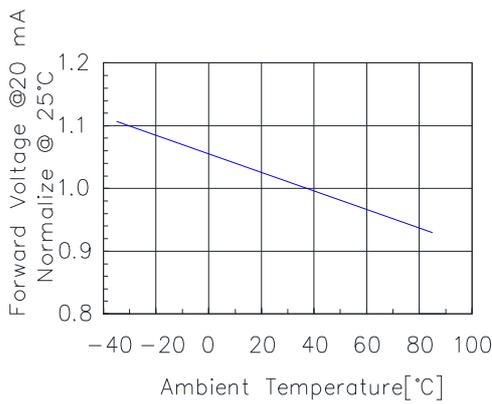


Fig 3. Forward Voltage vs. Temperature

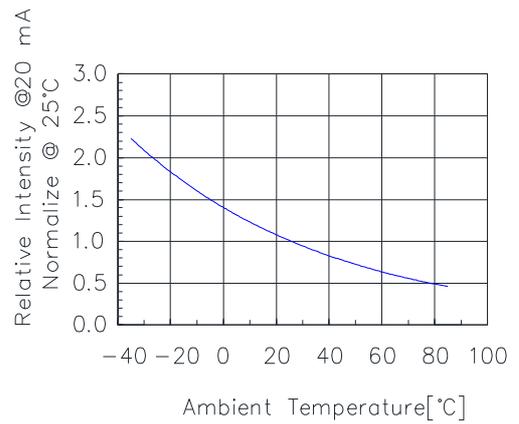


Fig 4. Relative Intensity vs. Temperature

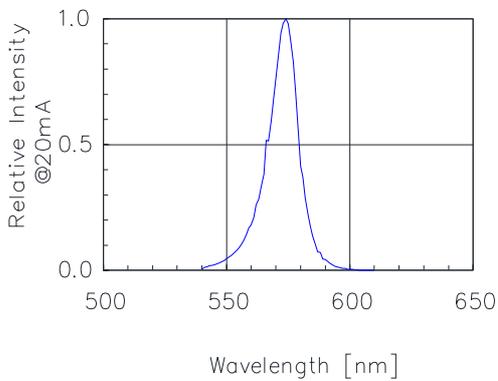
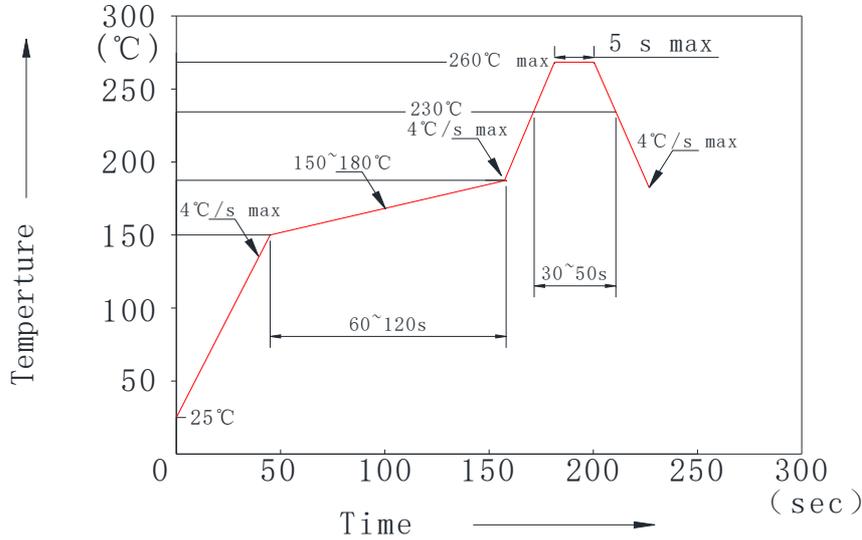
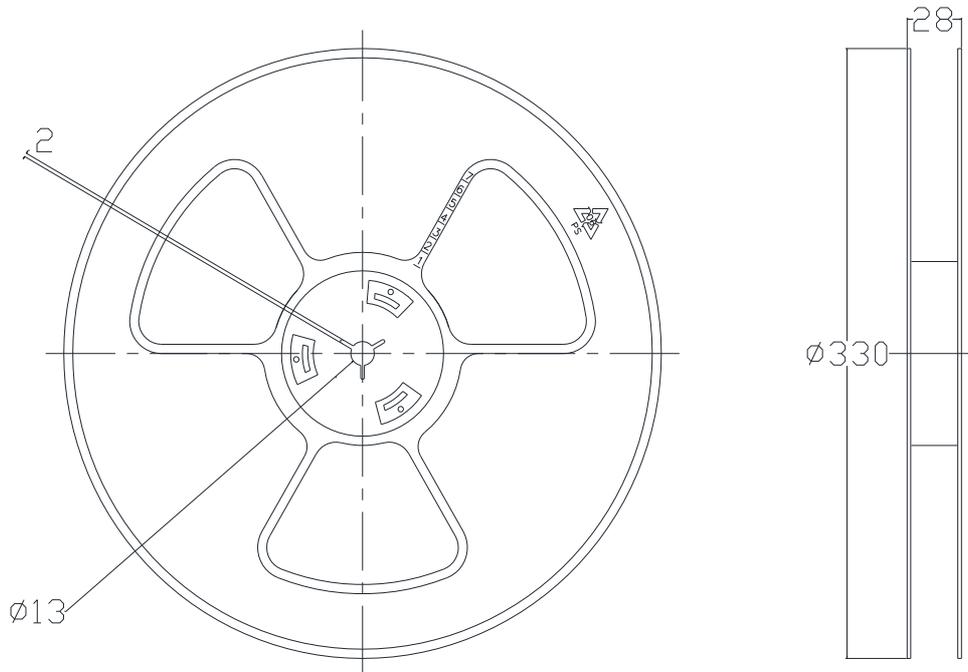


Fig 5. Relative Intensity vs. Wavelength

9、推荐的 SMT 焊接曲线 Recommended SMT condition:

NOTES:

1. We recommend the reflow temperature 245°C (+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

10、卷轴规格 REEL DIMENSIONS:


11、包装 PACKING & LABEL SPECIFICATIONS

